Enabling an Intelligent Planet

Advantech

AQD-D4U4GR21-HG
Datasheet

Rev. 0.0

2014-12-18

Description

AQD-D4U4GR21-HG is a DDR4 2133Mbps R-DIMM high-speed, memory module that use 9pcs of 512Mx 72 bits DDR4 SDRAM in FBGA package and a 4K bits serial EEPROM on a 288-pin printed circuit board.

AQD-D4U4GR21-HG is a Dual In-Line Memory Module and is intended for mounting into 288-pin edge connector sockets.

Synchronous design allows precise cycle control with the use of system clock. Data I/O transactions are possible on both edges of DQS. Range of operation frequencies, programmable latencies allow the same device to be useful for a variety of high bandwidth, high performance memory system applications.

Features

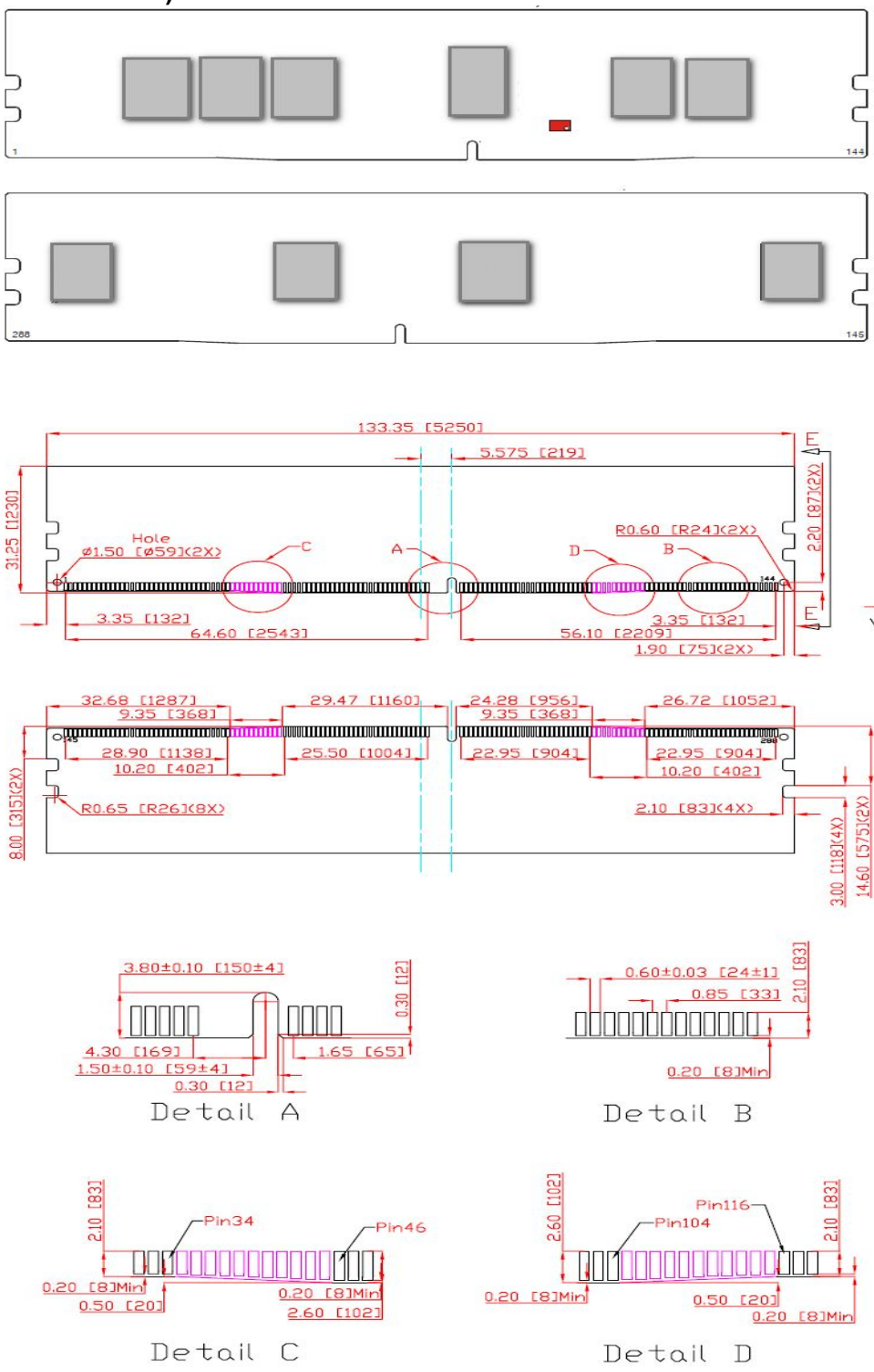
- RoHS compliant products.
- JEDEC standard 1.2V(1.14V~1.26V) Power supply
  VDDQ= 1.2V(1.14V~1.26V)
- VPP = 2.5V +0.25V / -0.125V
- Data transfer rates: PC4-2133
  Programmable CAS Latency: 9,11,12,13,14,15,16
- 8 bit pre-fetch
- Burst Length (BL) switch on-the-fly BL8 or BC4
- Bi-directional Differential Data-Strobe
- Supports ECC error correction and detection
- On Die Termination, Nominal, Park, and Dynamic ODT
- Serial presence detect with EEPROM
  Asynchronous reset
- PCB edge connector treated with 30u" Gold-Plating

Pin Identification

Symbol	Function
A0–A17[1], BA0~BA1	Address/Bank input
DQ0~DQ63	Bi-direction data bus.
DQS0_t–DQS17_t	Data Buffer data strobes
DQS0_c–DQS17_c	Data Buffer data strobes
CK0_t, CK1_t	Register clock input
CK0_c, CK1_c	Registert clocks input
ODT0 &ODT1	On-die termination control line
CS0_n–CS3_n	DIMM Rank Select Lines input.
RAS_n[2]	Row address strobe
CAS_n[3]	Column address strobe
WE_n[4]	Write Enable
DM0~DM7	Data masks/high data strobes
VDD	Core power supply
VDDQ	I/O driver power supply
V_{REF}CA	Command/address reference supply
V_{DD}SPD	SPD EEPROM power supply
SA0~SA2	I2C serial bus address select for EEPROM
SCL	I2C serial bus clock for EEPROM
SDA	I2C serial bus data for EEPROM
VSS	Ground
RESET_n	Set DRAMs Known State
VTT	DRAM I/O termination supply
VPP	SDRAM Supply
ALERT_n	Register ALERT_n output
EVENT_n	SPD signals a thermal event has occurred
RFU	Reserved for future use

1. Address A17 is only valid for 16 Gb x4 based SDRAMs.
2. RAS_n is a multiplexed function with A16.
3. CAS_n is a multiplexed function with A15.
4. WE_n is a multiplexed function with A14.

Dimensions (Unit: millimeter)

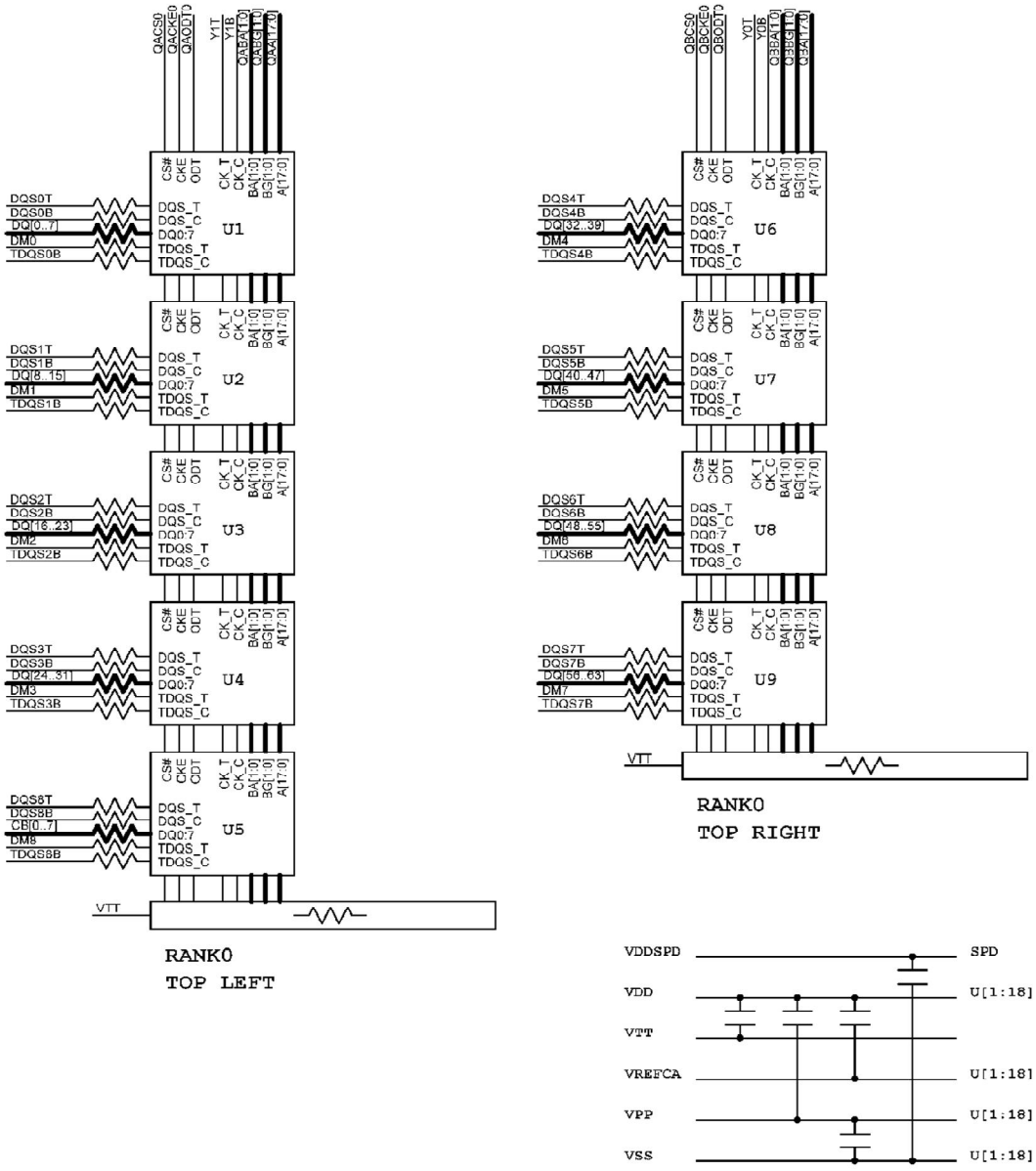


Note:1. Tolerances on all dimensions +/-0.15mm unless otherwise specified.

Pin Assignments

Pin	Front	Pin	Front	Pin	Front	Pin	Back	Pin	Back	Pin	Back	Pin	Back	Pin	Back
1	12V	41	DQS12C, TDQS12C	81	BA0	121	DQS15T,DM6, DBI6,TDQS15T	161	DQ9	201	CB3	241	VSS	281	VSS
2	VSS	42	VSS	82	RAS_n/A16	122	DQS15C, TDQS15C	162	VSS	202	VSS	242	DQ33	282	DQ59
3	DQ4	43	DQ30	83	VDD	123	VSS	163	DQS1C	203	CKE1	243	VSS	283	VSS
4	VSS	44	VSS	84	S0_n	124	DQ54	164	DQS1T	204	VDD	244	DQS4C	284	VDDSPD
5	DQ0	45	DQ26	85	VDD	125	VSS	165	VSS	205	RFU	245	DQS4T	285	SDA
6	VSS	46	VSS	86	CAS_n/A15	126	DQ50	166	DQ15	206	VDD	246	VSS	286	VPP
7	DQS9T,DM0, DBI0,TDQS9T	47	CB4	87	ODT0	127	VSS	167	VSS	207	BG1	247	DQ39	287	VPP
8	DQS9C, TDQS9C	48	VSS	88	VDD	128	DQ60	168	DQ11	208	ALERT_n	248	VSS	288	VPP
9	VSS	49	CB0	89	S1_n	129	VSS	169	VSS	209	VDD	249	DQ35		
10	QD6	50	VSS	90	VDD	130	DQ56	170	DQ21	210	A11	250	VSS		
11	VSS	51	DQS17T,DM8, DBI8,TDQS17T	91	ODT1	131	VSS	171	VSS	211	A7	251	DQ45		
12	DQ2	52	DQS17C, TDQS17C	92	VDD	132	DQS16T,DM7, DBI7,TDQS16T	172	DQ17	212	VDD	252	VSS		
13	VSS	53	VSS	93	S2_n,C[0]	133	DQS16C, TDQS16C	173	VSS	213	A5	253	DQ41		
14	DQ12	54	CB6	94	VSS	134	VSS	174	DQS2C	214	A4	254	VSS		
15	VSS	55	VSS	95	DQ36	135	DQ62	175	DQS2T	215	VDD	255	DQS5C		
16	DQ8	56	CB2	96	VSS	136	VSS	176	VSS	216	A2	256	DQS5T		
17	VSS	57	VSS	97	DQ32	137	DQ58	177	DQ23	217	VDD	257	VSS		
18	DQS10T,DM1, DBI1,TDQS10T	58	RESET_n	98	VSS	138	VSS	178	VSS	218	CK1T	258	DQ47		
19	DQS10C, TDQS10C	59	VDD	99	DQS13T,DM4, DBI4,TDQS13T	139	SA0	179	DQ19	219	CK1C	259	VSS		
20	VSS	60	CKE0	100	DQS13C, TDQS13C	140	SA1	180	VSS	220	VDD	260	DQ43		
21	DQ14	61	VDD	101	VSS	141	SCL	181	DQ29	221	VTT	261	VSS		
22	VSS	62	ACT_n	102	DQ38	142	VPP	182	VSS	222	PARITY	262	DQ53		
23	DQ10	63	BG0	103	VSS	143	VPP	183	DQ25	223	VDD	263	VSS		
24	VSS	64	VDD	104	DQ34	144	RFU	184	VSS	224	BA1	264	DQ49		
25	DQ20	65	A12	105	VSS	145	12V	185	DQS3C	225	A10_AP	265	VSS		
26	VSS	66	A9	106	DQ44	146	VREFCA	186	DQS3T	226	VDD	266	DQS6C		
27	DQ16	67	VDD	107	VSS	147	VSS	187	VSS	227	RFU	267	DQS6T		
28	VSS	68	A8	108	DQ40	148	DQ8	188	DQ31	228	WE_n/A14	268	VSS		
29	DQS11T,DM2, DBI2,TDQS11T	69	A6	109	VSS	149	VSS	189	VSS	229	VDD	269	DQ55		
30	DQS11C, TDQS11C	70	VDD	110	DQS14T,DM5, DBI5,TDQS14T	150	DQ1	190	DQ27	230	SAVE_n	270	VSS		
31	VSS	71	A3	111	DQS14C, TDQS14C	151	VSS	191	VSS	231	VDD	271	DQ51		
32	DQ22	72	A1	112	VSS	152	DQS0C	192	CB5	232	A13	272	VSS		
33	VSS	73	VDD	113	DQ46	153	DQS0T	193	VSS	233	VDD	273	DQ61		
34	DQ18	74	CK0T	114	VSS	154	VSS	194	CB1	234	A17,NC	274	VSS		
35	VSS	75	CK0C	115	DQ42	155	DQ7	195	VSS	235	C[2].NC	275	DQ57		
36	DQ28	76	VDD	116	VSS	156	VSS	196	DQS8C	236	VDD	276	VSS		
37	VSS	77	VTT	117	DQ52	157	DQ3	197	DQS8T	237	S3_n,C[1]	277	DQS7C		
38	DQ24	78	EVENT_n	118	VSS	158	VSS	198	VSS	238	SA2,RFU	278	DQS7T		
39	VSS	79	A0	119	DQ48	159	DQ13	199	CB7	239	VSS	279	VSS		
40	DQS12T,DM3, DBI3,TDQS12T	80	VDD	120	VSS	160	VSS	200	VSS	240	DQ37	280	DQ63		

4GB, 512Mx9 Module (1 Rank x8)



NOTE 1 ZQ pins for each SDRAM are connected to ground through individual resistors 240 ohm +/-1%

SA0 SA1 SA2

Serial PD w/ integrated Thermal sensor

Serial PD, no Thermal sensor

- This technical information is based on industry standard data and tests believed to be reliable. However, Advantech makes no warranties, either expressed or implied, as to its accuracy and assume no liability in connection with the use of this product. Advantech reserves the right to make changes in specifications at any time without prior notice.

Operating Temperature Condition

Parameter	Symbol	Rating	Unit	Note
Operating Temperature	TOPER	0 to 85	°C	1,2

Note: Operating Temperature is the case surface temperature on the center/top side of the DRAM. For the measurement conditions, please refer to JESD51-2 standard.

Absolute Maximum DC Ratings

Parameter	Symbol	Value	Unit	Note
Voltage on V_{DD} relative to Vss	VDD	-0.3 ~ 1.5	V	1
Voltage on V_{DDQ} pin relative to Vss	VDDQ	-0.3 ~ 1.5	V	1
Voltage on any pin relative to Vss	VIN, VOUT	-0.3 ~ 1.5	V	1
Storage temperature	T_{STG}	-55~+100	°C	1,2

Note:
1. Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Storage Temperature is the case surface temperature on the center/top side of the DRAM. For the measurement conditions, please refer to JESD51-2 standard.

AC & DC Operating Conditions

Recommended DC operating conditions

Parameter	Symbol	Voltage	Rating			Unit	Notes
			Min	Typ.	Max		
Supply voltage	VDD	1.2V	1.14	1.2	1.26	V	1,2,3
Supply voltage for Output	VDDQ	1.2V	1.14	1.2	1.26	V	1,2,3
I/O Reference Voltage (DQ)	$VREF_{DQ}$(DC)	1.2V	0.49*VDD	0.50*VDD	0.51*VDD	V	4
I/O Reference Voltage (CMD/ADD)	$VREF_{CA}$(DC)	1.2V	0.49*VDD	0.50*VDD	0.51*VDD	V	4
AC Input Logic High	VIH(AC)	1.2V	VREF+100	-	VDD^2	mV	
AC Input Logic Low	VIL(AC)	1.2V	VSS^2	-	VREF–100	mV	
DC Input Logic High	VIH(DC)	1.2V	VREF+75	-	VDD	mV	
DC Input Logic Low	VIL(DC)	1.2V	VSS	-	VREF-75	mV	

Note:
(1) Under all conditions VDDQ must be less than or equal to VDD.
(2) VDDQ tracks with VDD. AC parameters are measured with VDD and VDDQ tied together.
(3) The DC bandwidth is limited to 200MHz.
(4) The AC peak noise on VREF may not allow VREF to deviate from VREF(DC) by more than ±1% VDD (for reference: approx. ±12mV)

IDD Specification parameters Definition - 4GB (1 Rank x8)

Parameter	Symbol	DDR4 2133 CL15	Unit
One bank ACTIVATE-PRECHARGE current	IDD0[1]	279	mA
One bank ACTIVATE-PRECHARGE, wordline boost, IPP current	IPP0[1]	23.4	mA
One Bank Active-Read-Precharge Current	IDD1[1]	369	mA
Precharge Standby Current	IDD2N[2]	135	mA
Precharge standby ODT current	IDD2NT[1]	162	mA
Precharge Power-Down Current	IDD2P[2]	99	mA
Precharge Quiet Standby Current	IDD2Q[2]	135	mA
Active standby current	IDD3N[2]	243	mA
Active standby IPP current	IPP3N[2]	23.4	mA
Active Power-Down Current	IDD3P[2]	180	mA
Burst Read Current	IDD4R[1]	909	mA
Burst write current	IDD4W[1]	954	mA
Burst refresh current (1x REF)	IDD5B[1]	1080	mA
Burst refresh IPP current (1x REF)	IPP5B[1]	195.3	mA
Self refresh current: Normal temperature range (0–85°C)	IDD6N[2]	99	mA
Self refresh current: Extended temperature range (0–95°C)	IDD6E[2]	126	mA
Bank interleave read current	IDD7[1]	1242	mA
Bank interleave read IPP current	IPP7[1]	101.7	mA
Maximum power-down current	IDD8[2]	45	mA

Note: 1. One module rank in the active IDD/PP, the other rank in IDD2P/PP3N.
2. All ranks in this IDD/PP condition.
3.IDD current measure method and detail patterns are described on DDR4 component datasheet. Only for reference.

■ Timing Parameters & Specifications

Speed		DDR4-2133		Units
Parameter	Symbol	MIN	MAX	
Clock Timing				
Minimum Clock Cycle Time (DLL off mode)	tCK (DLL_OFF)	8	-	ns
Average Clock Period	tCK(avg)	tbd –(Definition tbd)		ps
Average high pulse width	tCH(avg)	0.48	0.52	tCK(avg)
Average low pulse width	tCL(avg)	0.48	0.52	tCK(avg)
Absolute Clock Period	tCK(abs)	tCK(avg)min + tJIT(per)min_to t	tCK(avg)max + tJIT(per)m ax_tot	tCK(avg)
Absolute clock HIGH pulse width	tCH(abs)	0.45	-	tCK(avg)
Absolute clock LOW pulse width	tCL(abs)	0.45	-	tCK(avg)
Clock Period Jitter- total	JIT(per)_tot	-0.1	0.1	UI
Clock Period Jitter- deterministic	JIT(per)_dj	TBD	TBD	UI
Clock Period Jitter during DLL locking period	tJIT(per, lck)	TBD	TBD	UI
Cycle to Cycle Period Jitter	tJIT(cc)_total	0.2		UI
Cycle to Cycle Period Jitter deterministic	tJIT(cc)_dj	TBD		UI
Cycle to Cycle Period Jitter during DLL locking period	tJIT(cc, lck)	TBD		UI
Duty Cycle Jitter	tJIT(duty)	TBD	TBD	UI
Cumulative error across 2 cycles	tERR(2per)	TBD	TBD	UI
Cumulative error across 3 cycles	tERR(3per)	TBD	TBD	UI
Cumulative error across 4 cycles	tERR(4per)	TBD	TBD	UI
Cumulative error across 5 cycles	tERR(5per)	TBD	TBD	UI
Cumulative error across 6 cycles	tERR(6per)	TBD	TBD	UI
Cumulative error across 7 cycles	tERR(7per)	TBD	TBD	UI
Cumulative error across 8 cycles	tERR(8per)	TBD	TBD	UI
Cumulative error across 9 cycles	tERR(9per)	TBD	TBD	UI
Cumulative error across 10 cycles	tERR(10per)	TBD	TBD	UI
Cumulative error across 11 cycles	tERR(11per)	TBD	TBD	UI
Cumulative error across 12 cycles	tERR(12per)	TBD	TBD	UI
Cumulative error across n = 13, 14 . . . 49, 50 cycles	tERR(nper)	TBD		UI
Command and Address Timing				
CAS_n to CAS_n command delay for same bank group	tCCD_L	5	-	nCK
CAS_n to CAS_n command delay for different bank group	tCCD_S	4	-	nCK
ACTIVATE to ACTIVATE Command delay to different bank group for 2KB page size	tRRD_S(2K)	Max(4nCK,5.3ns)	-	nCK
ACTIVATE to ACTIVATE Command delay to different bank group for 2KB page size	tRRD_S(1K)	Max(4nCK,3.7ns)	-	nCK
ACTIVATE to ACTIVATE Command delay to different bank group for 1/2KB page size	tRRD_S(1/2K)	Max(4nCK,3.7ns)	-	nCK
ACTIVATE to ACTIVATE Command delay to same bank group for 2KB page size	tRRD_L(2K)	Max(4nCK,6.4ns)	-	nCK
ACTIVATE to ACTIVATE Command delay to same bank group for 1KB page size	tRRD_L(1K)	Max(4nCK,5.3ns)	-	nCK
ACTIVATE to ACTIVATE Command delay to same bank group for 1/2KB page size	tRRD_L(1/2K)	Max(4nCK,5.3ns)	-	nCK
Four activate window for 2KB page size	tFAW_2K	30	-	ns
Four activate window for 1KB page size	tFAW_1K	21	-	ns
Four activate window for 1/2KB page size	tFAW_1/2K	15	-	ns
Delay from start of internal write transaction to internal read command for different bank group	tWTR_S	max(2nCK,2.5ns)	-	
Delay from start of internal write transaction to internal read command for same bank group	tWTR_L	max(4nCK,7.5ns)	-	
Internal READ Command to PRECHARGE Command delay	tRTP	max(4nCK,7.5ns)	-	
WRITE recovery time	tWR	15	-	ns
Write recovery time when CRC and DM are enabled	tWR_CRC _DM	tWR+max (5nCK,3.75ns)	-	ns
delay from start of internal write transaction to internal read command for different bank group with both CRC and DM enabled	tWTR_S_C RC_DM	tWTR_S+max (5nCK,3.75ns)	-	ns
delay from start of internal write transaction to internal read command for same bank group with both CRC and DM enabled	tWTR_L_C RC_DM	tWTR_L+max (5nCK,3.75ns)	-	ns
DLL locking time	tDLLK	TBD	-	nCK
Mode Register Set command cycle time	tMRD	8	-	nCK
Mode Register Set command update delay	tMOD	max(24nCK,15ns)	-	
Multi-Purpose Register Recovery Time	tMPRR	1	-	nCK
Multi Purpose Register Write Recovery Time	tWR_MPR	tMOD (min)	-	

Speed		DDR4-2133		Units
Parameter	Symbol	MIN	MAX	
Clock Timing				
CS_n to Command Address Latency				
CS_n to Command Address Latency	tCAL	4	-	nCK
DRAM Data Timing				
DQS_t,DQS_c to DQ skew, per group, per access	tDQSQ	-	TBD	tCK(avg)/2
DQS_t,DQS_c to DQ Skew deterministic, per group, per access	tDQSQ	-	TBD	tCK(avg)/2
DQ output hold time from DQS_t,DQS_c	tQH	TBD	-	tCK(avg)/2
DQ output hold time deterministic from DQS_t, DQS_c	tQH	TBD	-	UI
DQS_t,DQS_c to DQ Skew total, per group, per access;DBI enabled	tDQSQ	-	TBD	UI
DQ output hold time total from DQS_t, DQS_c; DBI enabled	tQH	TBD	-	UI
DQ to DQ offset , per group, per access referenced to DQS_t, DQS_c	tDQSQ	TBD	TBD	UI
Data Strobe Timing				
DQS_t,DQS_c differential output high time	tQSH	TBD	TBD	tCK(avg)/2
DQS_t,DQS_c differential output low time	tQSL	TBD	TBD	tCK(avg)/2
MPSM Timing				
Command path disable delay upon MPSM entry	tMPED	tMOD(min) + tCPDED(min)	-	
Valid clock requirement after MPSM entry	tCKMPE	tMOD(min) + tCPDED(min)	-	
Valid clock requirement before MPSM exit	tCKMPX	tCKSRX(min)	-	
Exit MPSM to commands not requiring a locked DLL	tXMP	TBD	-	
Exit MPSM to commands requiring a locked DLL	tXMPDLL	tXMP(min) + tXSDLL(min)	-	
CS setup time to CKE	tMPX_S	TBD	-	
CS hold time to CKE	tMPX_H	TBD	-	
Calibration Timing				
Power-up and RESET calibration time	tZQinit	1024	-	nCK
Normal operation Full calibration time	tZQoper	512	-	nCK
Normal operation Short calibration time	tZQCS	128	-	nCK
Reset/Self Refresh Timing				
Exit Reset from CKE HIGH to a valid command	tXPR	max (5nCK,tRFC(min)+ 10ns)	-	
Exit Self Refresh to commands not requiring a locked DLL	tXS	tRFC(min)+10ns	-	
SRX to commands not requiring a locked DLL in Self Refresh ABORT	tXS_ABORT(min)	tRFC4(min)+10ns	-	
Exit Self Refresh to ZQCL,ZQCS and MRS (CL,CWL,WR,RTP and Gear Down)	tXS_FAST (min)	tRFC4(min)+10ns	-	
Exit Self Refresh to commands requiring a locked DLL	tXSDLL	tDLLK(min)	-	
Minimum CKE low width for Self refresh entry to exit timing	tCKESR	tCKE(min)+1nCK	-	
Valid Clock Requirement after Self Refresh Entry (SRE) or Power-Down Entry (PDE)	tCKSRE	max(5nCK,10ns)	-	
Valid Clock Requirement after Self Refresh Entry (SRE) or Power-Down when CA Parity is enabled	tCKSRE_PAR	max (5nCK,10ns)+PL	-	
Valid Clock Requirement before Self Refresh Exit (SRX) or Power-Down Exit (PDX) or Reset Exit	tCKSRX	max(5nCK,10ns)	-	
Power Down Timing				
Exit Power Down with DLL on to any valid command; Exit Precharge Power Down with DLL frozen to commands not requiring a locked DLL	tXP	max (4nCK,6ns)	-	
CKE minimum pulse width	tCKE	max (3nCK, 5ns)	-	
Command pass disable delay	tCPDED	4	-	nCK
Power Down Entry to Exit Timing	tPD	tCKE(min)	9*tREFI	
Timing of ACT command to Power Down entry	tACTPDEN	2	-	nCK
Timing of PRE or PREA command to Power Down entry	tPRPDEN	2	-	nCK
Timing of RD/RDA command to Power Down entry	tRDPDEN	RL+4+1	-	nCK
Timing of WR command to Power Down entry (BL8OTF, BL8MRS, BC4OTF)	tWRPDEN	WL+4+(tWR/ tCK(avg))	-	nCK
Timing of WRA command to Power Down entry (BL8OTF, BL8MRS, BC4OTF)	tWRAPDEN	WL+4+WR+1	-	nCK
Timing of WR command to Power Down entry (BC4MRS)	tWRPBC4DEN	WL+2+(tWR/ tCK(avg))	-	nCK
Timing of WRA command to Power Down entry (BC4MRS)	tWRAPBC4DEN	WL+2+WR+1	-	nCK
Timing of REF command to Power Down entry	tREFPDEN	1	-	nCK
Timing of MRS command to Power Down entry	tMRSPDEN	tMOD(min)	-	

Speed		DDR4-2133		Units
Parameter	Symbol	MIN	MAX	
Clock Timing				
PDA Timing				
Mode Register Set command cycle time in PDA mode	tMRD_PDA	max(16nCK,10ns)		
Mode Register Set command update delay in PDA mode	tMOD_PDA	tMOD		
ODT Timing				
Asynchronous RTT turn-on delay (Power-Down with DLL frozen)	tAONAS	1.0	9.0	ns
Asynchronous RTT turn-off delay (Power-Down with DLL frozen)	tAOFAS	1.0	9.0	ns
RTT dynamic change skew	tADC	0.3	0.7	tCK(avg)
Write Leveling Timing				
First DQS_t/DQS_n rising edge after write leveling mode is programmed	tWLMRD	40	-	nCK
DQS_t/DQS_n delay after write leveling mode is programmed	tWLDQSEN	25	-	nCK
Write leveling setup time from rising CK_t, CK_c crossing to rising DQS_t/DQS_n crossing	tWLS	0.13	-	tCK(avg)
Write leveling hold time from rising DQS_t/DQS_n crossing to rising CK_t, CK_ crossing	tWLH	0.13	-	tCK(avg)
Write leveling output delay	tWLO	0	9.5	ns
Write leveling output error	tWLOE			ns
CA Parity Timing				
Commands not guaranteed to be executed during this time	tPAR_UNKNOWN	-	Max(2nCK,3ns)	
Delay from errant command to ALERT_n assertion	tPAR_ALERT_ON	-	PL+6ns	
Pulse width of ALERT_n signal when asserted	tPAR_ALERT_PW	64	128	nCK
Time from when Alert is asserted till controller must start providing DES commands in Persistent CA parity mode	tPAR_ALERT_RSP	-	57	nCK
Parity Latency	PL	4		nCK
CRC Error Reporting				
CRC error to ALERT_n latency	tCRC_ALERT	-	13	ns
CRC ALERT_n pulse width	CRC_ALERT_PW	6	10	nCK
tREFI				
tRFC1 (min)	2Gb	160	-	ns
	4Gb	260	-	ns
	8Gb	350	-	ns
	16Gb	TBD	-	ns
tRFC2 (min)	2Gb	110	-	ns
	4Gb	160	-	ns
	8Gb	260	-	ns
	16Gb	TBD	-	ns
tRFC4 (min)	2Gb	90	-	ns
	4Gb	110	-	ns
	8Gb	160	-	ns
	16Gb	TBD	-	ns

SERIAL PRESENCE DETECT SPECIFICATION (AQD-D4U4GR21-HG Serial Presence Detect)

Byte	Function Described	Function		HEX Value
0	Number of Bytes Used / Number of Bytes in SPD Device / CRC Coverage	SPD Total: 512Bytes, SPD Used : 384Bytes		23
1	SPD Revision	Version 1.0		10
2	Key Byte / DRAM Device Type	DDR4 SDRAM		0C
3	Key Byte / Module Type	RDIMM		01
4	SDRAM Density and Banks	4 bank group / 4 bank	4Gb	84
5	SDRAM Addressing	Row : 15	Column : 10	19
6	SDRAM Device Type	Mono / Single die		00
7	SDRAM Optional Features	Unlimited MAC		08
8	SDRAM Thermal and Refresh Options	-		00
9	Other SDRAM Optional Features	PPR Supported		40
10	Reserved	-		00
11	Module Nominal Voltage, VDD	1.2v		03
12	Module Organization	1Rank	x8	01
13	Module Memory Bus Width	8bit ECC	64bits	0B
14	Module Thermal Sensor	Thermal Sensor on module		80
15~16	Reserved	-		00
17	Timebases	MTB: 125ps	FTB: 1ps	00
18	SDRAM Minimum Cycle Time (tCKAVGmin)	0.938 ns		08
19	SDRAM Maximum Cycle Time (tCKAVGmax)	1.5 ns		0C
20	CAS Latencies Supported, First Byte	CL 9,11,12,13,14		F4
21	CAS Latencies Supported, Second Byte	CL 15,16		03
22	CAS Latencies Supported, Third Byte	-		00
23	CAS Latencies Supported, Fourth Byte	-		00
24	Minimum CAS Latency Time(tAAmin)	13.5 ns		6C
25	Minimum RAS to CAS Delay Time (tRCDmin)	13.5 ns		6C
26	Minimum Row Precharge Delay Time (tRPmin)	13.5 ns		6C
27	Upper Nibbles for tRASmin and tRCmin	-		11
28	Minimum Active to Precharge Delay Time (tRASmin), Least Significant Byte	33 ns		08
29	Minimum Active to Active/Refresh Delay Time (tRCmin), Least Significant Byte	46.5 ns		74
30	Minimum Refresh Recovery Delay Time (tRFC1min), Least Significant Byte	260 ns		20
31	Minimum Refresh Recovery Delay Time (tRFC1min), Most Significant Byte			08
32	Minimum Refresh Recovery Delay Time (tRFC2min), Least Significant Byte	160 ns		00
33	Minimum Refresh Recovery Delay Time (tRFC2min), Most Significant Byte			05
34	Minimum Refresh Recovery Delay Time (tRFC4min), Least Significant Byte	110 ns		70
35	Minimum Refresh Recovery Delay Time (tRFC4min), Most Significant Byte			03
36	Upper Nibble for tFAW	21 ns		00
37	Minimum Four Activate Window Delay Time (tFAWmin), Least Significant Byte			A8
38	Minimum Activate to Activate Delay Time (tRRD_Smin), different bank group	3.7 ns		1E
39	Minimum Activate to Activate Delay Time (tRRD_Lmin), same bank group	5.3 ns		2B
40	Minimum CAS to CAS Delay Time (tCCD_Lmin), same bank group	5.355 ns		2B
41~59	Reserved, Base Configuration Section	-		00
60	Connector to SDRAM Bit Mapping	DQ0, DQ1, DQ2, DQ3		0E
61	Connector to SDRAM Bit Mapping	DQ4, DQ5, DQ6, DQ7		2E
62	Connector to SDRAM Bit Mapping	DQ8, DQ9, DQ10, DQ11		16
63	Connector to SDRAM Bit Mapping	DQ12, DQ13, DQ14, DQ15		36
64	Connector to SDRAM Bit Mapping	DQ16, DQ17, DQ18, DQ19		16
65	Connector to SDRAM Bit Mapping	DQ20, DQ21, DQ22, DQ23		36
66	Connector to SDRAM Bit Mapping	DQ24, DQ25, DQ26, DQ27		16
67	Connector to SDRAM Bit Mapping	DQ28, DQ29, DQ30, DQ31		36
68	Connector to SDRAM Bit Mapping	CB0-3		0E
69	Connector to SDRAM Bit Mapping	CB4-7		2E
70	Connector to SDRAM Bit Mapping	DQ32, DQ33, DQ34, DQ35		23
71	Connector to SDRAM Bit Mapping	DQ36, DQ37, DQ38, DQ39		04
72	Connector to SDRAM Bit Mapping	DQ40, DQ41, DQ42, DQ43		2B
73	Connector to SDRAM Bit Mapping	DQ44, DQ45, DQ46, DQ47		0C
74	Connector to SDRAM Bit Mapping	DQ48, DQ49, DQ50, DQ51		2B
75	Connector to SDRAM Bit Mapping	DQ52, DQ53, DQ54, DQ55		0C
76	Connector to SDRAM Bit Mapping	DQ56, DQ57, DQ58, DQ59		23
77	Connector to SDRAM Bit Mapping	DQ60, DQ61, DQ62, DQ63		04
78~116	Reserved, Base Configuration Section	-		00

117	Fine Offset for Minimum CAS to CAS Delay Time(tCCD_Lmin), same bank group	-0.02ns		EC
118	Fine Offset for Minimum Activate to Activate Delay Time(tRRD_Lmin), different bank group	-0.076ns		B4
119	Fine Offset for Minimum Activate to Activate Delay Time(tRRD_Smin), same bank group	-0.05ns		CE
120	Fine Offset for Minimum Activate to Activate/Refresh Delay Time(tRCmin)	0ns		00
121	Fine Offset for Minimum Row Precharge Delay Time(tRPmin)	0ns		00
122	Fine Offset for Minimum RAS to CAS Delay Time(tRCDmin)	0ns		00
123	Fine Offset for Minimum CAS Latency Time(tAAmin)	0ns		00
124	Fine Offset for SDRAM Maximum Cycle Time(tCKAVGmax)	0ns		00
125	Fine Offset for SDRAM Minimum Cycle Time(tCKAVGmin)	-0.063ns		C1
126	Cyclical Redundancy Code for Base Configuration Section, LSB	CRC-CCITT(LOW)		37
127	Cyclical Redundancy Code for Base Configuration Section, MSB	CRC-CCITT(HIGH)		91
128	(Registered): Raw Card Extension, Module Nominal Height	Revision 0	31.25mm	11
129	(Registered): Module Maximum Thickness	-		11
130	(Registered): Reference Raw Card Used	Raw Card D	Revision 0	03
131	(Registered): DIMM Module Attributes	1 Register/1 Row each side		05
132	(Registered): RDIMM Thermal Heat Spreader Solution	-		00
133	(Registered): Register Manufacturer ID Code, LSB	Montage		86
134	(Registered): Register Manufacturer ID Code, MSB			32
135	(Registered): Register Revision Number	-		B1
136	(Registered): Address Mapping from Register to DRAM	Standard		00
137	(Registered): Register Output Drive Strength for Control	Light Drive		00
138	(Registered): Register Output Drive Strength for CK	Light Drive		00
139~253	(Registered): Reserved	-		00
254	(Registered): Cyclical Redundancy Code for Module Specific Section, LSB	CRC-CCITT(LOW)		EF
255	(Registered): Cyclical Redundancy Code for Module Specific Section, MSB	CRC-CCITT(HIGH)		9E
256~319	Hybrid Memory Architecyure Specific Parameters	-		00
320	Module Manufacturer ID Code, LSB	ADATA		04
321	Module Manufacturer ID Code, MSB			CB
322	Module ID: Module Manufacturing Location	*Note: 1		-
323	Module ID: Module Manufacturing Date(Year)	*Note: 2		-
324	Module ID: Module Manufacturing Date(Week)	*Note: 3		-
325~328	Module ID : Module Serial Number	*Note: 4		-
329~348	Module Part Number	*Note: 5		-
349	Module Revision Code	-		00
350	SDRAM Manufacturer's JEDEC ID Code, LSB	Hynix Technology		80
351	SDRAM Manufacturer's JEDEC ID Code, MSB			AD
352	DRAM Stepping	-		FF
353~381	Manufacturer's Specific Data	*Note: 6		-
382	Reserved	-		00
383	Reserved	-		00
384~511	End User Programmable	*Note: 7		-

Note : 1. Byte 322 -- Manufacturing location by manufacturing location (00:Taiwan /01:China)
2. Byte 323 -- Module manufacturing date by year (YY).
3. Byte 324 -- Module manufacturing date by week (WW).
4. Bytes 325~328 -- Module Serial Number.
5. Bytes 329~348 -- Manufacturer Part Number by module part number , (Unused digits are coded as ASCII blanks (20h)).
6. Bytes 353~381 -- These bytes are undefined and can be used for ADATA's own purpose. Digits are coded as 00h except the following:
   6-1. Bytes 353~367 -- Manufacturer's Specific Data by working order number.
   6-2. Bytes 368~381 -- Manufacturer's Specific Data by SPD naming number.
7. Bytes 384~511 -- These bytes are undefined and can be used for ADATA's own purpose. Digits are coded as 00h except the following:
   7-1. Bytes 384 -- The byte is coded as ADh.